

RoHS Compliant

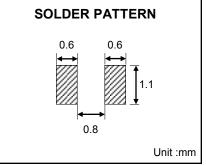
MINIATURE CERAMIC SMD TUNING FORK CRYSTAL (2 x 1.2 x 0.6mm)

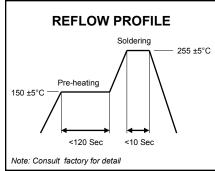
FEATURES:

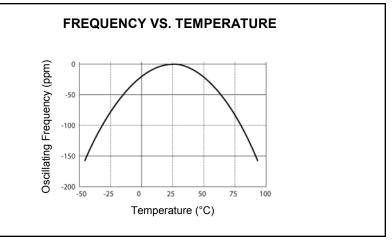
- SMALLEST CERAMIC SMD PACKAGE 32.768KHz
- EXCELLENT HEAT RESISTANCE
- -40°C TO 85°C OPERATING TEMPERATURE



MODEL	CS2012	
FREQUENCY	32.768KHz	
FREQUENCY TOLERANCE @ 25°C ± 2°C	± 20ppm max.	
OPERATING TEMPERATURE	-40°C to 85°C	
TURN OVER TEMPERATURE	25°C ± 5°C	
TEMPERATURE COEFFICIENT	-0.045 x 10 ⁻⁶ / °C ² Max	
STORAGE TEMPERATURE	-40°C to 85°C	
LOAD CAPACITANCE	12.5pF	
SHUNT CAPACITANCE	2.0pF typical	
ESR	90KΩ max.	
DRIVE LEVEL	0.5uW max	
AGING (First Year)	± 3.0ppm max. @ 25°C ± 3°C	







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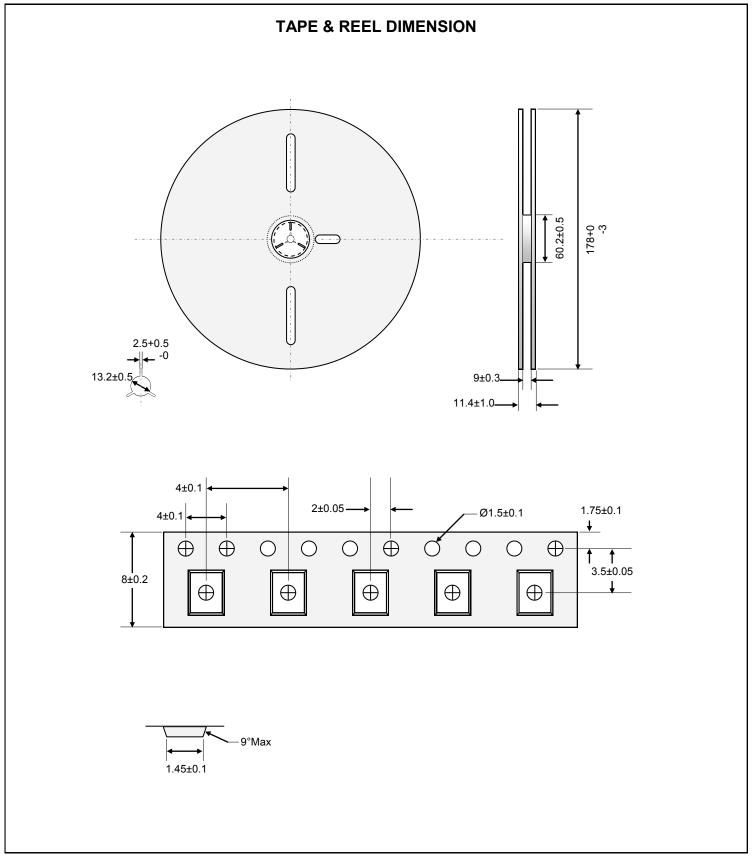
RELIABILITY TEST

T-411	Took oo u diki ou	Specification	
restitems	Test Items Test condition		SMD
1. Gross Leak Test	FC-0 125°C / 30sec	No continuous bubble	
2. Fine Leak Test	Bombing of He 4kg/cm ² for 2 hours	Less than 5*10^-8atm. c.c./sec, Helium	
3. Drop Test	A. ~19.999MHz(Fund.) -> 100cm height B. 20~29.000MHz(Fund.) -> 50cm height C. 30~ MHz(Fund.) -> 20cm height On hard wooden surface / 3times (thickness more that 30mm)	∆F≤±10ppm, C.I within spec.	∆F≤±10ppm, C.I within spec.
4. Vibration Test	Freq. range: 10~55Hz Peak to peak amplitude: 1.5mm 3direction(X,Y,Z) each 60min.	∆F≤±10ppm, C.I within spec.	∆F≤±10ppm, C.I within spec.
5. Resistance to Soldering Test B tic	A. IR Reflow furnace with the condition 2 times. Peak temp. 260±3°C, 10±1 sec.	NA	∆F≤±10ppm, C.I within spec. For SMD type only.
	B. Dip terminals in a 245±5°C solder station(pool) Dipping depth 0.5mm(Min) Dipping time 5±0.5sec.	At least 90% by 30X magnification of each dipped area shall be covered by fresh solder. For DIP type only.	NA
6. Bending Test	Bending cycle: 1 cycle 0°-> 45°-> 0° -> 45° -> 0°	∆F≤±15ppm, C.I within spec. For DIP type only.	NA
7. Shearing Test	Weight: 5N, Test duration: 10±1 sec	NA	∆F≤±10ppm, C.I within spec. For SMD type only.
8. Low Temp. Exposure Test	-40±3°C, 240 ± 12hrs	∆F≤±10ppm, C.I within spec.	∆F≤±10ppm, C.I within spec.
9. Aging Test	85±3°C, 240 ± 12hrs	∆F≤±10ppm, C.I within spec.	∆F≤±10ppm, C.I within spec.
10. High Temp. & Humidity Test	85±5°C & 85%±5% R.H., 240 ± 12 hrs	∆F≤±10ppm, C.I within spec.	∆F≤±10ppm, C.I within spec.
11. Temperature Cycling Test	-25±3°C/15±3min ~ 85±3°C/15±3min 15cycles	∆F≤±10ppm, C.I within spec.	∆F≤±10ppm, C.I within spec.

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